

## Hyperfast Rectifier, 5 A FRED Pt<sup>®</sup>


**SMC (DO-214AB)**


### FEATURES

- Hyperfast recovery time, reduced  $Q_{rr}$  and soft recovery
- 175 °C maximum operating junction temperature
- For PFC CRM/CCM, snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Designed and qualified according to JEDEC<sup>®</sup>-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	5 A
$V_R$	600 V
$V_F$ at $I_F$	1.2 V
$t_{rr}$ typ.	30 ns
$T_J$ max.	175 °C
Package	SMC (DO-214AB)
Circuit configuration	Single

### DESCRIPTION/APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_L = 73\text{ °C}$ <sup>(1)</sup>	5	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$ , 10 ms sine pulse	110	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

**Note**

<sup>(1)</sup> Mounted on PCB with minimum pad size

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\ \mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 5\ \text{A}$	-	1.65	1.95	
		$I_F = 5\ \text{A}, T_J = 150\text{ °C}$	-	1.2	1.4	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	3	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	100	
Junction capacitance	$C_T$	$V_R = 600\ \text{V}$	-	7.8	-	pF

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	30	-	ns
		$I_F = 1.0\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	35	-	
		$I_F = 0.5\text{ A}$ , $I_R = 1\text{ A}$ , $I_{rr} = 0.25\text{ A}$	-	-	35	
		$T_J = 25\text{ }^\circ\text{C}$	-	23	-	
		$T_J = 125\text{ }^\circ\text{C}$	-	38	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	3.5	-	A
		$T_J = 125\text{ }^\circ\text{C}$	-	5.4	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	41	-	nC
		$T_J = 125\text{ }^\circ\text{C}$	-	111	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-55	-	175	$^\circ\text{C}$
Thermal resistance, junction to case	$R_{thJC}^{(1)}$		-	-	14	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{thJA}^{(1)}$		-	-	80	
Approximate Weight			0.24			g
			0.008			oz.
Marking device		Case style SMC (DO-214AB)	5H6			

**Note**

(1) Mounted on PCB with minimum pad size

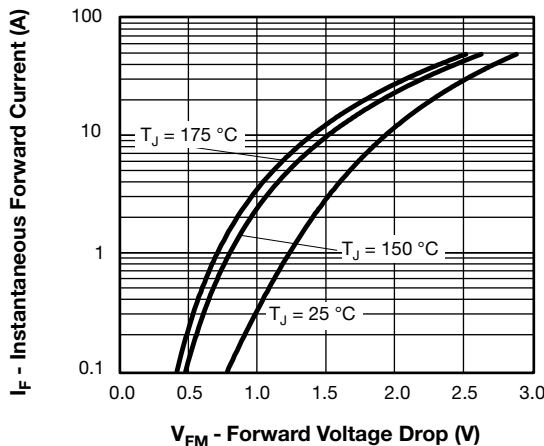


Fig. 1 - Typical Forward Voltage Drop Characteristics

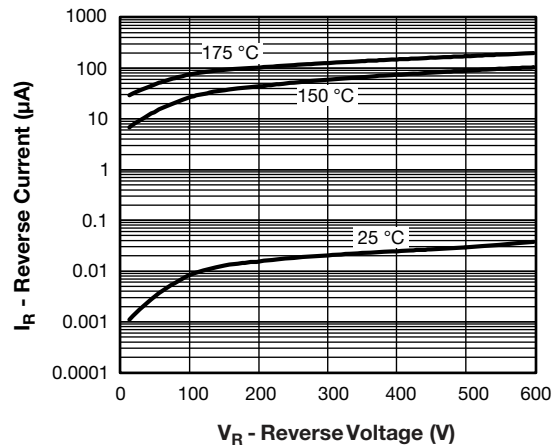


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

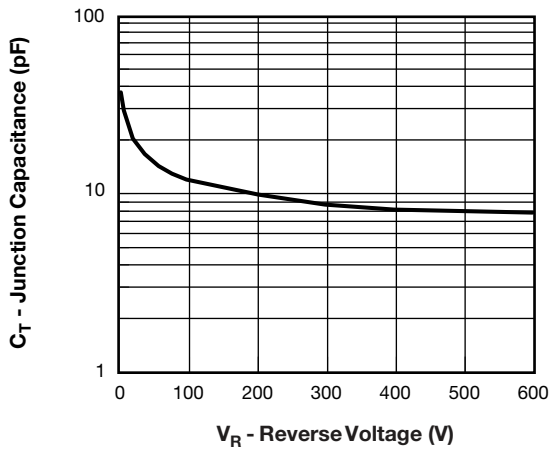


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

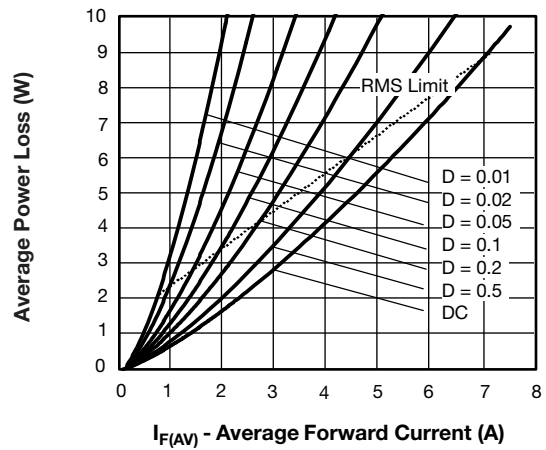


Fig. 5 - Forward Power Loss Characteristics

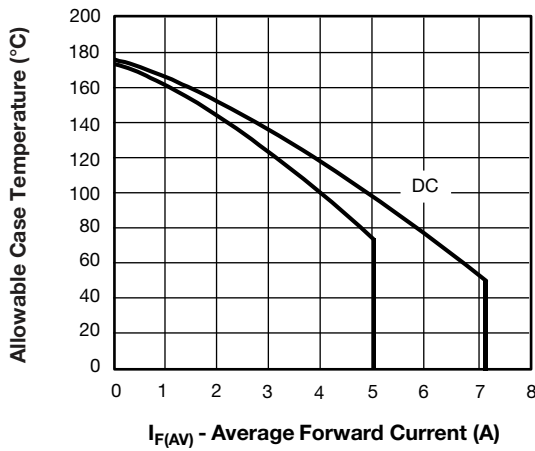


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

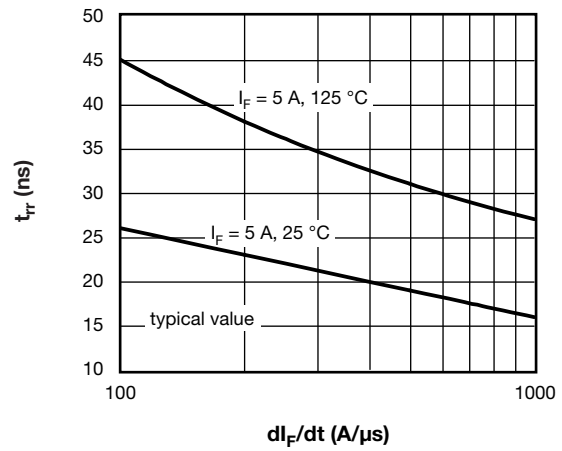


Fig. 6 - Typical Reverse Recovery vs.  $dI_F/dt$

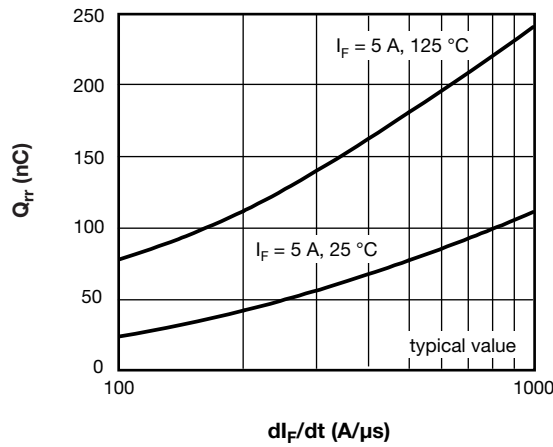
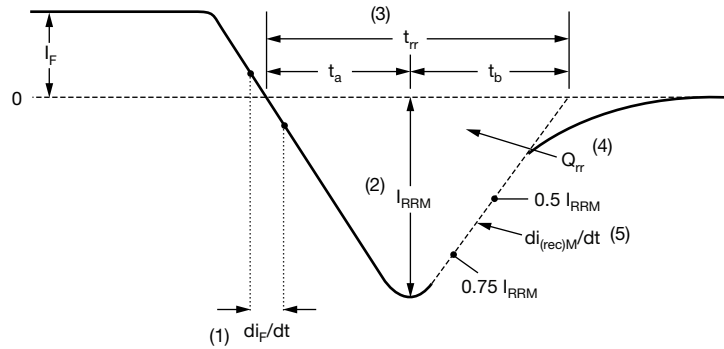


Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$



- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 8 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>5</b>	<b>E</b>	<b>C</b>	<b>H</b>	<b>06</b>	<b>-M3</b>
	①	②	③	④	⑤	⑥	⑦

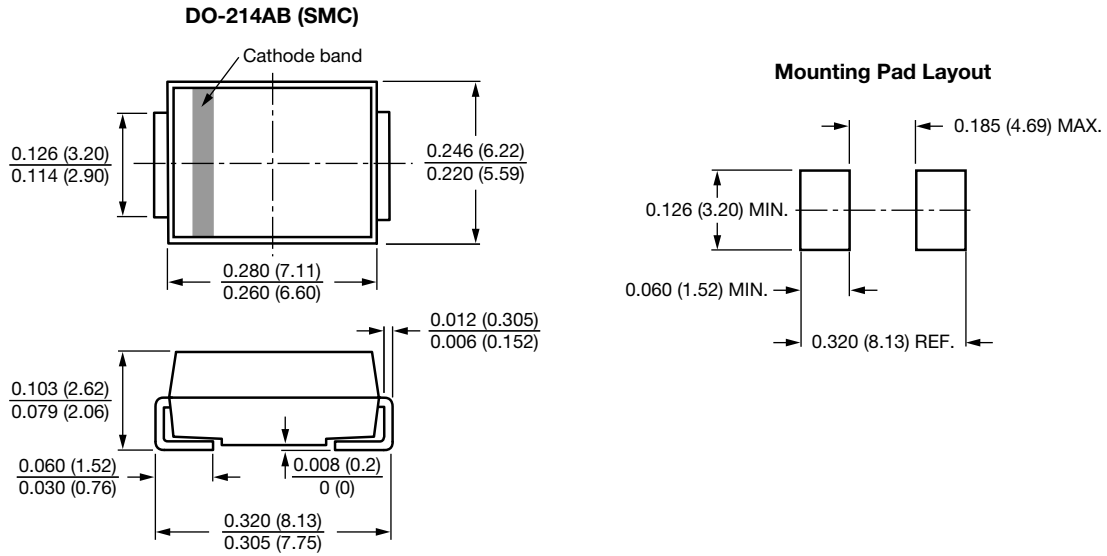
- 1** - Vishay Semiconductors product
- 2** - Current rating (5 = 5 A)
- 3** - Circuit configuration:  
E = single diode
- 4** - C = SMC package
- 5** - Process type,  
H = hyperfast recovery
- 6** - Voltage code (06 = 600 V)
- 7** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

<b>ORDERING INFORMATION</b> (Example)			
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-5ECH06-M3/9AT	9AT	3500	13" diameter plastic tape and reel

<b>LINKS TO RELATED DOCUMENTS</b>	
Dimensions	<a href="http://www.vishay.com/doc?95402">www.vishay.com/doc?95402</a>
Part marking information	<a href="http://www.vishay.com/doc?95472">www.vishay.com/doc?95472</a>
Packaging information	<a href="http://www.vishay.com/doc?95404">www.vishay.com/doc?95404</a>
SPICE model	<a href="http://www.vishay.com/doc?96709">www.vishay.com/doc?96709</a>

## SMC

**DIMENSIONS** in inches (millimeters)





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